



Material Content Data Sheet



Sales Product Name		BSC440N10NS3 G		Issued		25. January 2018		
MA#		MA001637810						
Package		PG-TDSON-8-40		Weight*		111.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.830	0.74	0.74	7435	7435
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	iron	7439-89-6	0.049	0.04		436	
	non noble metal	copper	7440-50-8	48.649	43.59	43.64	435858	436425
	non noble metal	copper	7440-50-8	0.061	0.05	0.05	543	543
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	543	543
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		758	
	plastics	epoxy resin	-	6.680	5.98		59843	
	inorganic material	silicondioxide	60676-86-0	35.511	31.82	37.88	318151	378752
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13618	13618
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1420	1420
solder	non noble metal	tin	7440-31-5	0.023	0.02		202	
	noble metal	silver	7440-22-4	0.028	0.03		253	
	non noble metal	lead	7439-92-1	1.078	0.97	1.02	9654	10109
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		46	
	non noble metal	iron	7439-89-6	0.017	0.02		152	
	non noble metal	copper	7440-50-8	16.910	15.15	15.17	151500	151698
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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